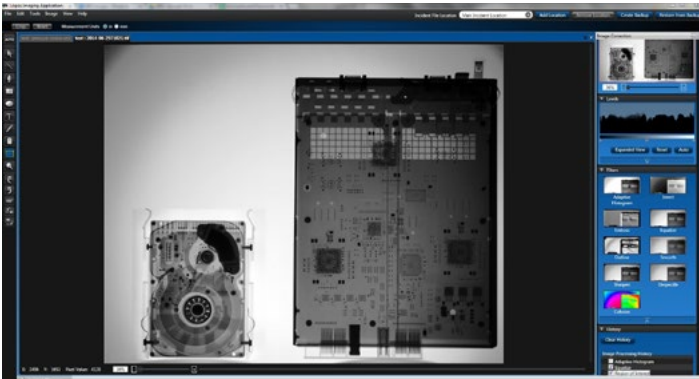# BRSInnovations

LOGOS IMAGING

NEOS III
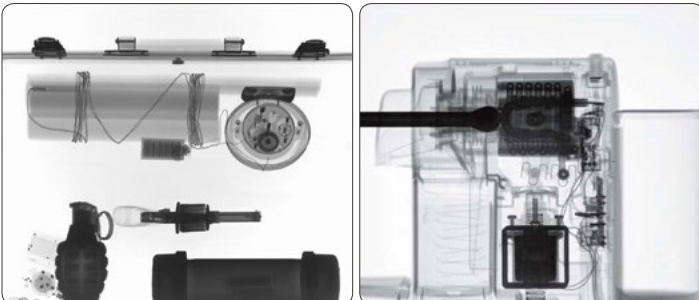## Portable Direct Radiography Imaging System
10" x 13" DR Panel

Logos Imaging's NEOS III is the latest small format DR imaging system specifically designed to withstand the rigors of harsh environments. The imager housing is cast Mg and includes shielding to allow use with higher X-ray energies. The design of the NEOS III provides shock, vibration, and water ingress protection giving users unparalleled confidence in the system's performance wherever the job site is located. The system also offers the advantages of built in wireless communications and a removable battery that provides two hours of operation for situations where ultra-portability and short-range communications are desirable.

FEATURES

► Wired and Wireless Panel Operation
► 8 mm Bottom Border
► High Resolution and Sensitivity, 127 µm Pixel Size, 3.9 lp/mm
► Multiple Scintillator Options

Logos Imaging Application software is intuitive allowing users to quickly and easily see what they need

SPECIFICATIONS:

► Technology: Amorphous Silicon with TFT
► Scintillator: Gadox
► Pixel Area: 32.5 x 26.0 cm, 12.8" x 10.2"
► Pixel Matrix: 2560 x 2048 pixels
► Pixel Size: 127 µm
► AD Conversion: 16 bits
► Limiting Resolution: 3.9 lp/mm
► Communications Interface: Wireless: 2.4 GHz (5 GHz Optional); Wired: LAN
► Communications Range: Wireless: 50 m or up to 400 m with interface (line of sight, using 2.4 GHz); Wired: option 50 m to 200 m
► Image Transfer: Wired: 5 seconds; Wireless: 9 seconds
► X-ray Energy Range: 40 - 330 kV
► Weight: 3.3 kg (7.3 lbs)
► Dimensions (Panel): 38.5 x 32.0 x 1.8 cm 15.2" x 12.6" x 0.7"
► Power: 100-240 VAC (50-60 Hz), 2A using included power supply; 14.4 V, 93 Wh, Li-Ion hot-swappable battery pack
► Operating Temperature: Wired: -20 to 50 °C (-4 to 122 °F); Wireless: 0 to 40 °C (32 to 104 °F)
► Storage Temperature: -20 to 50 °C (-4 to 122 °F)
► PC Specs (Minimum): Core i7 Processor, 4 GB RAM, 500 GB hard disk, 14" 1600 x 900 display, Windows 7 Professional